## REMARKS

Claims 1-20 were originally filed in the present application. Pursuant to a restriction requirement, claims 19 and 20 were subsequently canceled without prejudice or disclaimer. Claims 1-6 were also subsequently canceled without prejudice or disclaimer, and new claims 21-28 were added.

Currently, claims 7-18 and 21-28 are canceled without prejudice or disclaimer, and new claims 29-48 are added. Consequently, claims 29-48 are currently pending in the present application.

Reconsideration of this application in light of the above amendments and the following remarks is requested.

### Rejections under 35 U.S.C. §112

Claim 21 was rejected under 35 U.S.C. §112, second paragraph, as allegedly being indefinite. However, claim 21 is currently canceled without prejudice or disclaimer. Accordingly, Applicant respectfully requests the Examiner withdraw the §112 rejection.

### Rejections under 35 U.S.C. §§102 and 103

The previously-pending claims were rejected under 35 U.S.C. §§102 and 103 in view of the following references, whether cited separately or in various combinations:

- U.S. Patent No. 5,153,710 to McCain ("McCain");
- U.S. Patent No. 5,089,877 to Queyssac ("Queyssac");
- Japanese Patent No. 6-85162 to Matsushita ("Matsushita");
- U.S. Patent No. 4,971,868 to Tucholski, et al. ("Tucholski");
- U.S. Patent No. RE35,765 to Tuttle ("Tuttle");
- U.S. Patent No. 6,833,290 to Knapp, et al. ("Knapp," also published as U.S. Pat. Pub. No. 2003/0201520); and
- U.S. Patent No. 6,346,343 to Notten, et al. ("Notten").

However, these claims are currently canceled without prejudice or disclaimer. Accordingly, Applicant respectfully requests the Examiner withdraw the current rejections under §§102 and 103.

**New claim 29**

Claim 29 recites:

> 29. An integrated circuit package, comprising:
> a lead frame assembly including a central support member and a plurality of conductive leads, wherein the central support member has opposing first and second major surfaces, and wherein the plurality of conductive leads are radially disposed about the periphery of the central support member;
> an integrated circuit die coupled to the first surface of the central support member and having a plurality of bond pads;
> a power cell coupled to the second surface of the central support member and comprising a cathode layer, an anode layer, and a separator layer interposing the cathode and anode layers, wherein the cathode layer is doped with a first impurity type and the anode layer is doped with a second, opposite impurity type, and wherein the first and second impurity types are selected from an n-type impurity and a p-type impurity;
> an electrode including a planar body and a terminal extending from the body, wherein the body is coupled to the power cell opposite the central support member;
> a plurality of first wire bonds each coupling one of the plurality of bond pads and one of the plurality of conductive leads; and
> a second wire bond having a first terminus coupled to one of the plurality of bond pads and a second terminus coupled to the terminal of the electrode, wherein the terminal has an arcuate shape configured to position the second terminus of the second wire bond in a reference plane that is coincident with the first surface of the central support member.

To anticipate or render obvious claim 29, the above-listed references must teach or suggest each and every element of claim 29, whether the references are taken separately or together. However, at least in the context of claim 29, none of the references teaches or suggests a power cell comprising a cathode layer, an anode layer, and a separator layer interposing the cathode and anode layers, wherein the cathode layer is doped with a first impurity type and the anode layer is doped with a second, opposite impurity type, and wherein the first and second impurity types are selected from an n-type impurity and a p-type impurity, among other elements of claim 29. Moreover, also in the context of claim 29, none of the references teaches or suggests an electrode including a planar body and a terminal extending from the body, wherein the terminal has an arcuate shape configured to position a second terminus of a second wire bond in a reference plane that is coincident with a first surface of a central support member, among other elements of claim 29.

Therefore, a §102 or §103 rejection of claim 29 cannot be supported by any of the above-listed references.

**New claim 39**

Claim 39 recites:

> 39. An integrated circuit package, comprising:
> a lead frame assembly including a central support member and a plurality of conductive leads, wherein the central support member has opposing first and second major surfaces, and wherein the plurality of conductive leads are radially disposed about the periphery of the central support member;
> an integrated circuit die coupled to the first surface of the central support member and having a plurality of bond pads;
> an electrode including a planar body and a terminal extending from the body;
> a power cell interposing the body and the integrated circuit die and coupled directly to at least one of the integrated circuit die and the body;
> a plurality of first wire bonds each coupling one of the plurality of bond pads and one of the plurality of conductive leads;
> a second wire bond having a first terminus coupled to one of the plurality of bond pads and a second terminus coupled to the terminal of the electrode, wherein the terminal has an arcuate shape configured to position the second terminus of the second wire bond in a reference plane that is coincident with the first surface of the central support member; and
> an insulating layer encapsulating the central support member, the integrated circuit die, the electrode, the power cell, the plurality of first wire bonds, and the second wire bond, collectively.

To anticipate or render obvious claim 39, the above-listed references must teach or suggest each and every element of claim 39, whether the references are taken separately or together. However, at least in the context of claim 39, none of the references teaches or suggests an electrode including a planar body and a terminal extending from the body, wherein the terminal has an arcuate shape configured to position a second terminus of a second wire bond in a reference plane that is coincident with a first surface of a central support member, among other elements of claim 39. Moreover, also in the context of claim 39, none of the references teaches or suggests an insulating layer encapsulating a central support member, an integrated circuit die, an electrode, a power cell, a plurality of first wire bonds, and a second wire bond, collectively, among other elements of claim 39.

Therefore, a §102 or §103 rejection of claim 39 cannot be supported by any of the above-listed references.

**New claim 45**

Claim 45 recites:

> 45. An integrated circuit package, comprising:
> a lead frame assembly including a central support member (CSM) having opposing first and second CSM surfaces;
> an integrated circuit die (ICD) having opposing first and second ICD surfaces, wherein the first ICD surface is coupled directly to the first CSM surface;
> a laminated, solid state power cell having a cathode layer implanted with a first impurity type, an anode layer implanted with a second impurity type that is opposite the first impurity type, and a separator layer interposing the cathode and anode layers, wherein a first one of the cathode and anode layers is coupled directly to the second CSM surface;
> an electrode having a substantially planar body and a terminal extending from the body, wherein the electrode body is coupled directly to a second one of the cathode and anode layers;
> a wire bond having first and second ends, wherein the first end is coupled directly to a bond pad located on the second ICD surface, and wherein the second end is coupled directly to the electrode terminal in a reference plane that is coincident with the first CSM surface; and
> an insulating layer encapsulating the CSM, the ICD, the power cell, the electrode, and the wire bond, collectively.

To anticipate or render obvious claim 45, the above-listed references must teach or suggest each and every element of claim 45, whether the references are taken separately or together. However, at least in the context of claim 45, none of the references teaches or suggests a laminated, solid state power cell having a cathode layer implanted with a first impurity type, an anode layer implanted with a second impurity type that is opposite the first impurity type, and a separator layer interposing the cathode and anode layers, among other elements of claim 45. Moreover, also in the context of claim 45, none of the references teaches or suggests a wire bond having first and second ends, wherein the first end is coupled directly to a bond pad located on a second ICD surface, and wherein the second end is coupled directly to an electrode terminal in a reference plane that is coincident with a first CSM surface, among other elements of claim 45. Furthermore, also in the context of claim 45, none of the references teaches or suggests an insulating layer encapsulating a CSM, an ICD, a power cell, an electrode, and a wire bond, collectively, among other elements of clam 45.

Therefore, a §102 or §103 rejection of claim 45 cannot be supported by any of the above-listed references.

## Conclusion

It is clear from all of the foregoing that independent claims 29, 39, and 45 are in condition for allowance. Dependent claims 30-38, 40-44, and 46-48 depend from and further limit independent claims 29, 39, and 45 and, therefore, are allowable as well.

It is believed that all matters set forth in the Office Action have been addressed, and that claims 29-48 are in condition for allowance. Favorable consideration and an early indication of the allowability of the claims are respectfully requested. Should the Examiner deem that an interview with Applicant's undersigned attorney would expedite consideration, the Examiner is invited to call the undersigned attorney at the telephone number indicated below.

Respectfully submitted,

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